D//S GLOBAL

Feature	Standard	Advanced
Materials	RIGID: CEM1, CEM3, FR4, Teflon FLEX: FR4, Kapton, Polymide IMS: AL BASED	RIGID: on demand: low/super low/ultra low loss material IMS: CU BASED
Minimum dielectric thickness	0.05mm for PCB 0.025mm for FPC	0.025mm for PCB 0.012mm for FPC
Layer count	1 – 8 L	24 L
HDI / Buried – blind via	Y	Y
Maximum board size (mm)	546 X 622	600 X 1100
Minimum board thickness (mm) 2L	0.4mm for PCB 0.05mm for 1L FPC 0.12mm for 2L FPC	0.15mm for PCB 0.05mm for 1L FPC 0.12mm for 2L FPC
Maximum board thickness (mm)	3.2mm	on demand
Minimum track / gap Inner layer(mil) – based on copper weight	0.075mm	0.05mm
Minimum track / gap Outer layer (mil) – based on copper weight	0.075mm	0.05mm
Surface finish	ENIG / OSP / I Ag / HASL (lead) / HASL (Leadfree) / Immersion Sn /	Hard Gold / ENEPIG /Hard Gold + OSP / Combined Finishes
Layer to layer registration	0.05mm	25µm
Minimum hole (mech) (mm/mil)	0.15mm	0.1mm
Minimum hole (laser) (mm/mil)	0.075	0,05
Aspect ratio PTH	08:01	01:01
Aspect ration BVH	0.8:1	01:01
Finish hole tolerance (PTH)	± 0.076mm	± 0.05mm
Finish hole tolerance (NPTH)	± 0.05mm	± 0.0375mm
Maximum Cu weight OL	4oz	10oz
Maximum Cu weight IL	4oz	10oz
Controlled impedance (+/- X%)	± 10%	± 5%

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